



PDC-001-HP (115V)
PDC-002-HP (230V)

With twice the cleaning rate as the Expanded Plasma Cleaner, the High Power Expanded Plasma Cleaner is a versatile instrument, suitable for etching organic thin films (10-100 nm) as well as surface activation and modification.

FEATURES

- Compact, tabletop unit
- Adjustable RF power settings (Low, Medium, High)
- Maximum RF power of 45W (Low RF power equivalent to High RF power on PDC-001 / PDC-002)
- Includes 6" diameter x 6.5" length Pyrex chamber
- Hinged door with viewing window
- Active fan cooling
- Integral switch for a vacuum pump (not available in CE model)
- 1/8" NPT metering valve to qualitatively control gas flow and chamber pressure
- 1/8" NPT 3-way valve to quickly switch from introducing gas, venting, and isolating the chamber
- Weight: 37 lbs | Size: 11" H x 18" W x 9" D

REQUIREMENTS

- Gas-compatible vacuum pump with minimum pump speed of 23 L/min and ultimate total pressure of 200 mTorr or less
- Compatible vacuum pumps available
 - For pumping nonreactive gases (air, N₂, Ar), see our Oil-Based Vacuum Pumps
 - For pumping concentrated or pure oxygen gas, see our Oxygen Service Pumps

OPTIONAL ACCESSORIES

- PlasmaFlo Gas Flow Mixer for quantitative control of up to two (2) process gases and monitoring of chamber pressure
- Quartz chambers for reactive gas applications and contamination-sensitive applications
- Sample trays to facilitate loading and unloading of small samples for batch processing